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Raspberry Pi Goes Professional

Originally developed as an educational tool, the Raspberry Pi's combination of computer power and low cost has been attracting the interest of professional designers looking for quicker solutions to complex applications.

There has been a gradual shift in thinking about the proper role of small yet powerful single board computers (SBCs) that follow a modular approach in providing extensibility for the basic compute module. Some boards were originally devised as development platforms targeting professional designers, but have since made their way into the hands of hobbyists and makers. Other boards, originally developed for hobbyist and educational applications, are now making their way into professional use, with the result that the distinctions between these various uses is starting to blur.

X-FAB doubles 6-inch SiC foundry capacity at Lubbock fab

In response to increased customer demand for high-efficiency power semiconductor devices, analog/mixed-signal and specialty foundry X-FAB Silicon Foundries SE of Erfurt, Germany plans to double the 6-inch silicon carbide (SiC) process capacity at its fab in Lubbock, TX, USA.

In preparation for manufacturing 6-inch SiC wafers, X-FAB Texas has purchased a second heated ion implanter, for delivery by the end of 2018 and production release in first-quarter 2019 (in time to meet projected near-term demand).

Claiming to have been the first wafer foundry to offer SiC manufacturing on 6-inch wafers, X-FAB says that its doubling in SiC process capacity demonstrates its commitment to SiC technology and the SiC foundry business model.

X-FAB says that advantages of its 6-inch SiC process capabilities for power semiconductors include superior highvoltage operation, significantly lower transistor on-resistance, much lower transmission and switching losses, extended high-temperature operation (as high as 400°F/204°C), higher thermal conductivity, very high-frequency operation, and lower parasitic capacitance. The firm's SiC process capabilities allow customers to realize highefficiency power semiconductor devices including high-power MOSFETs, JFETs and Schottky diodes.

Hazy 5G Growth Agenda Nags Telecom Chiefs

Mobile phone users in the Finnish city of Tampere and the Estonian capital Tallinn were the first in the world to be connected to a commercial 5G network in June when Elisa, the Finnish mobile phone company, switched on the first live next-generation service and made a video call between the two cities.

Finland has a long history as a pioneer of wireless technology so it was little surprise that an operator from the Nordic country had beaten its global rivals to the punch by offering 5G packages for €50 a month. There was just one catch — there are no 5G smartphones available on the market and there will not be until midway through 2019. Elisa is in effect selling something called 5G that will deliver a 4G service.

Automotive Chipset Supports DSRC And C-V2X

LONDON — Israel-based Autotalks has launched what it says is the first global V2X (vehicle-to-everything) solution supporting both dedicated short-range communications (DSRC) and the C-V2X direct communications (PC5 protocol) in a single automotive-qualified chipset.

In recent years, V2X diverged into two different technologies — DSRC and C-V2X — with fundamentally different architectures, making it difficult to harmonize a single global solution.

While DSRC-based V2X is deployed in the U.S., Europe, and Japan, C-V2X is gaining momentum in other regions, including China. Autotalks says that its chipset now supports DSRC based on the 802.11p/ITS-G5 standards and C-V2X based on 3GPP specifications. It delivers dual-mode (DSRC and C-V2X) functionality on the company's existing automotive-qualified AEC-Q100 Grade 2 chipsets and maintains the present API, enabling a global dual-mode V2X platform to be delivered much more quickly than before.

With \$65M, ThinCI Joins Elite AI Startup Club

MADISON, Wis. — With a host of chip startups — each claiming development of a unique processing architecture ideally suited for Al/machine learning— all hot and bothered in an overheated Al market, how can you tell who's ahead of whom?

In the absence of commonly applied benchmarks and commercial silicon on the open market, here's where money speaks volumes. How much investment a startup has been able to raise thus far is a useful yardstick.

With a recently closed Series C round of \$65 million, ThinCl Inc., an AI processor company (EI Dorado Hills, California), joins an exclusive club of well-heeled AI hardware startups. Other members include Wave Computing, which has raised \$117.3 million, Cerebras at \$112 million, and Graphcore at \$110 million.